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# **THE WORLDWIDE IC PACKAGING MARKET**

***2009 EDITION***

**The Most Comprehensive Report Available  
On The Global IC Packaging Industry**

## **Report Highlights**

- **Industry Overview**
  - ◆ **Semiconductor Industry Analysis**
  - ◆ **SATS Company Financial Analysis**
  - ◆ **Global Economic Factors**
- **Worldwide IC Packaging Market Forecasts, 2009–2013**
  - ◆ **Units**
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# The Worldwide IC Packaging Market, 2009 Edition

## Synopsis

After an unprecedented six years of double-digit unit growth, the semiconductor industry faltered in late 2008 as the global economic crisis struck hard. So, where is the industry headed now and what are the implications for the IC packaging industry? *New Venture Research (NVR)*, in the **2009 Edition of The Worldwide IC Packaging Market**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market.

The report begins with NVR's views on the state of the semiconductor industry, along with a top level forecast (see Figure 1). This discussion includes factors bearing on individual semiconductor products as well as global economic factors. The financial performance of the publicly-traded SATS companies' is also addressed.

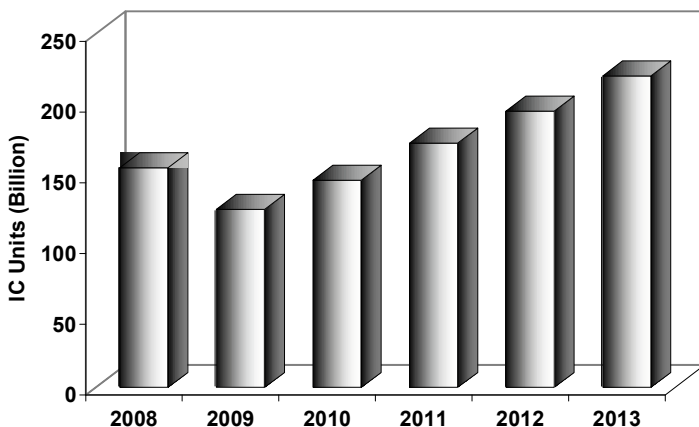


Figure 1 IC Unit Forecast

Following this high-level review, the report presents forecasts for each semiconductor product type, and segments these products by package family and I/O count range. Packaging revenue figures are displayed for each segment, based on prices charged in the contract assembly market. The package families are then rolled up by I/O count and semiconductor product. In doing so, the report generates the total value of the IC packaging industry.

Next, the report presents NVR's continuing, extensive coverage of the packaging contractor market. Packaging contractors will continue to assume a larger share of the world's IC packaging business. The report breaks the contractor market down by package families and major product categories, providing units and revenue for each category. To help you further assess this group of companies, the report profiles the activities of the world's largest contractors and the packages they offer.

**The Worldwide IC Packaging Market, 2009 Edition** continues NVR's leadership position in assessing the status and future of IC packaging. This report will provide you with an effective and economical tool for assessing the future of this market. The report sells for \$2995, with extra copies \$350 each. Each copy includes both a hard-bound version and a single-user PDF on CD-ROM. Corporate licensing is available—contact us for pricing. Order your copies today!

## About the Authors

**Sandra Winkler** is the senior analyst for IC packaging at New Venture Research (NVR). She began her analyst career as an independent consultant to the telecommunications industry nearly 20 years ago. Since 1995, Ms. Winkler has authored all of NVR's widely cited reports on IC packaging. She has spoken at numerous industry conferences and has written articles for a variety of trade publications. Ms. Winkler has an MBA from Santa Clara University.

**Steve Berry** was President and Principal Analyst of Electronic Trend Publications (ETP). Mr. Berry has been responsible for the direction of all aspects of ETP's broad-ranging research portfolio since 1993. In the eighteen years prior to joining ETP, he held a variety of engineering, manufacturing management, and business development positions with General Electric and Xerox. Mr. Berry holds a BS in Engineering from North Carolina State University and an MBA from Stanford University.

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EEMS	Signetics
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